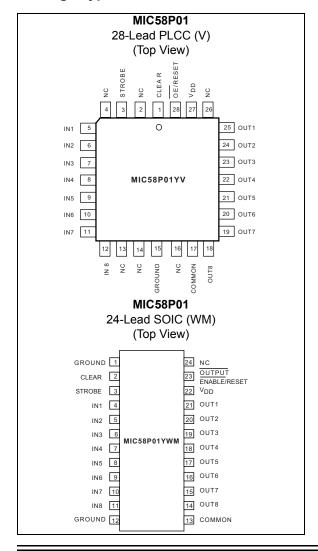


8-Bit Parallel-Input Protected Latched Driver

Features

- · 4.4 MHz Minimum Data Input Rate
- · High-Voltage, High-Current Outputs
- Per-Output Overcurrent Shutdown (500 mA Typical)
- Undervoltage Lockout
- · Thermal Shutdown
- Output Transient Protection Diodes
- CMOS, PMOS, NMOS, and TTL Compatible Inputs
- · Internal Pull-Down Resistors
- · Low-Power CMOS Latches

Package Types



General Description

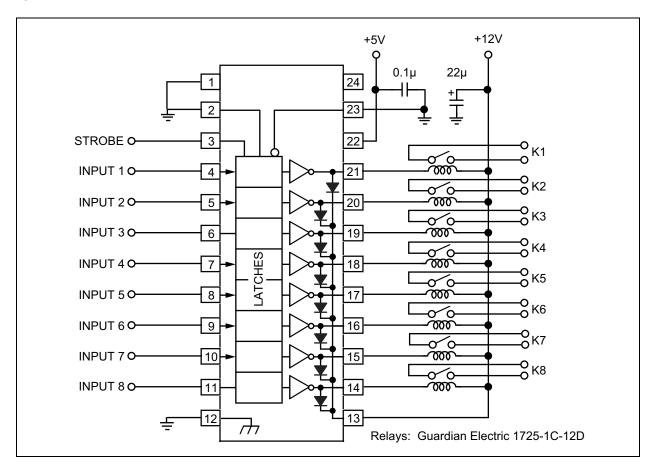
The MIC58P01 parallel-input latched driver is a high-voltage (80V), high-current (500 mA) integrated circuit comprised of eight CMOS data latches, a bipolar Darlington transistor driver for each latch, and CMOS control circuitry for the common CLEAR, STROBE, and OUTPUT ENABLE functions. Similar to the MIC5801, additional protection circuitry supplied on this device includes thermal shutdown, undervoltage lockout (UVLO), and overcurrent shutdown.

The bipolar/CMOS combination provides an extremely low-power latch with maximum interface flexibility. The MIC58P01 has open-collector outputs capable of sinking 500 mA and integral diodes for inductive load transient suppression with a minimum output breakdown voltage rating of 80V (50V sustaining). The drivers may be connected in parallel for higher load current capability.

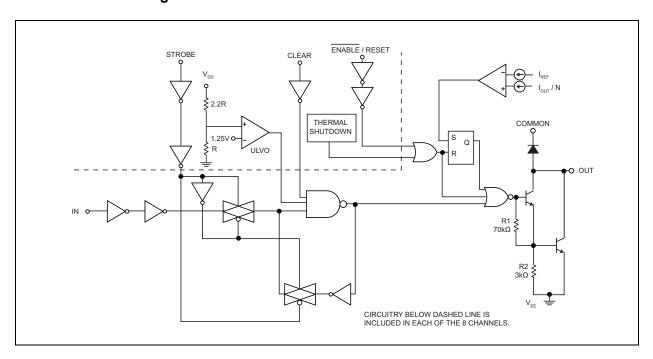
With a 5V logic supply, the MIC58P01 will typically operate at better than 5 MHz. With a 12V logic supply, significantly higher speeds are obtained. The CMOS inputs are compatible with standard CMOS, PMOS, and NMOS circuits. TTL circuits may require pull-up resistors.

Each of these eight outputs has an independent overcurrent shutdown of 500 mA. Upon current shutdown, the affected channel will turn off until V_{DD} is cycled or the ENABLE/RESET pin is pulsed high. Current pulses less than 2 μs will not activate current shutdown. Temperatures above 165°C will shut down all outputs. The UVLO circuit disables the outputs at low V_{DD} ; hysteresis of 0.5V is provided.

Typical Application Circuit



Functional Block Diagram



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Output Voltage (V _{CE})	+80V
Logic Supply Voltage (V _{DD})	
Input Voltage Range (V _{IN})	0.3V to V _{DD} + 0.3V
Maximum Operating Ambient Temperature (T _{A(MAX)})	+85°C
Minimum Operating Ambient Temperature (T _{A(MIN)})	
ESD Rating (Note 1)	

Operating Ratings ††

† Notice: Exceeding the absolute maximum ratings may damage the device.

†† Notice: The device is not guaranteed to function outside its operating ratings.

Note 1: Microchip CMOS devices have input-static protection, but are susceptible to damage when exposed to extremely high static electrical charges.

ELECTRICAL CHARACTERISTICS

Electrical Characteristics: V _{DD} = 5V, T _A = +25°C, unless otherwise noted. Note 1								
Parameter	Sym.	Min.	Тур.	Max.	Units	Conditions		
Output Lookage Current		1	_	50	^	V _{CE} = 80V, T _A = +25°C		
Output Leakage Current	ICEX	1	_	100	μA	V _{CE} = 80V, T _A = +70°C		
		1	0.9	1.1		I _C = 100 mA		
Collector-Emitter Saturation Voltage	V _{CE(SAT)}	1	1.1	1.3	V	I _C = 200 mA		
Cataration voltage			1.3	1.6		I _C = 350 mA		
Input Voltage (Low)	V _{IN(0)}		_	1.0	٧	_		
		10.5	_	1		V _{DD} = 12V		
Input Voltage (High)	V _{IN(1)}	8.5	_	1	V	V _{DD} = 10V		
		3.5	_			V _{DD} = 5V, Note 2		
		50	200			V _{DD} = 12V		
Input Resistance	R _{IN}	50	300	1	kΩ	V _{DD} = 10V		
		50	600	_		V _{DD} = 5V		

- Note 1: Specification for packaged product only.
 - 2: Operation of these devices with standard TTL or DTL may require the use of appropriate pull-up resistors to ensure a minimum logic "1".
 - **3:** Undervoltage Lockout is guaranteed to release device at no more than 4.5V, and disable the device at no less than 3.0V.

ELECTRICAL CHARACTERISTICS (CONTINUED)

Electrical Characteristics: V _{DD} = 5V, T _A = +25°C, unless otherwise noted. Note 1								
Parameter	Sym.	Min.	Тур.	Max.	Units	Conditions		
		_	3.3	4.5		One Driver ON, V _{DD} = 12V, Outputs Open		
	I _{DD(1ON)}	_	3.1	4.5	mA	One Driver ON, V _{DD} = 10V, Outputs Open		
		_	2.4	3.6		One Driver ON, V _{DD} = 5V, Outputs Open		
Supply Courset		_	6.4	10.0		All Drivers ON, V _{DD} = 12V, Outputs Open		
Supply Current	I _{DD(ON)}	_	6.0	9.0	mA	<u> </u>		
		_	4.7	7.5		All Drivers ON, V _{DD} = 5V, Outputs Open		
	I _{DD(OFF)}	_	3.0	4.5	4	All Drivers OFF, V _{DD} = 12V, Outputs Open, Inputs = 0V		
		_	2.2	3.6	mA	All Drivers OFF, V _{DD} = 5V, Outputs Open, Inputs = 0V		
Clamp Diode Leakage	I _R	_		50		V _R = 80V, T _A = +25°C		
Current		_		100	μA	V _R = 80V, T _A = +70°C		
Overcurrent Threshold	I _{LIM}	_	500		mA	Per Output		
Start-Up Voltage	V _{SU}	3.5	4.0	4.5	V	Note 3		
Minimum Operating V _{DD}	V _{DD(MIN)}	3.0	3.5	4.0	V	_		
Clamp Diode Forward Voltage	V _F	_	1.7	2.0	V	I _F = 350 mA		
Thermal Shutdown	_		165		°C	_		
Thermal Shutdown Hystersis	_	_	10	_	°C	_		

- Note 1: Specification for packaged product only.
 - 2: Operation of these devices with standard TTL or DTL may require the use of appropriate pull-up resistors to ensure a minimum logic "1".
 - **3:** Undervoltage Lockout is guaranteed to release device at no more than 4.5V, and disable the device at no less than 3.0V.

TRUTH TABLE

INI	Strobo	trobe Clear Output Enable	Output Frahla	OUT _N		
IN _N	Strobe		t – 1	t		
0	1	0	0	Х	OFF	
1	1	0	0	X	ON	
X	Х	1	X	X	OFF	
X	X	X	1	X	OFF	
X	0	0	0	ON	ON	
Х	0	0	0	OFF	OFF	

Legend: X = Irrelevant; t - 1 = Previous output state; t = Present output state.

Information present at an input is transferred to its latch when the STROBE is high. A high CLEAR input will set all latches to the output OFF condition regardless of the Data or STROBE input levels. A high OUTPUT ENABLE will set all outputs to the OFF condition, regardless of any other input conditions. When the OUTPUT ENABLE is low, the outputs depend on the state of their respective latches. If current shutdown is activated, the OUTPUT ENABLE must be pulsed high to restore operation. Overtemperature faults are not latched and require no reset pulse.

TEMPERATURE SPECIFICATIONS

Parameters	Sym.	Min.	Тур.	Max.	Units	Conditions	
Temperature Ranges							
Maximum Operating Temperature Range	T _A	-55	_	+85	°C	_	
Storage Temperature Range	T _S	-65	_	+125	°C	_	
Operating Temperature Range	T _A	-40	_	+85	°C	_	

Note 1: The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature and the thermal resistance from junction to air (i.e., T_A , T_J , θ_{JA}). Exceeding the maximum allowable power dissipation will cause the device operating junction temperature to exceed the maximum +125°C rating. Sustained junction temperatures above +125°C can impact the device reliability.

2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

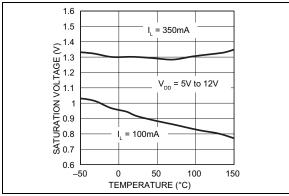


FIGURE 2-1: Output Saturation Voltage vs. Temperature.

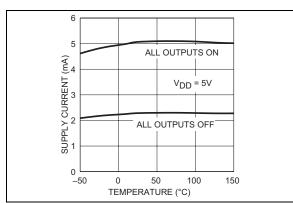


FIGURE 2-2: Supply Current vs. Temperature.

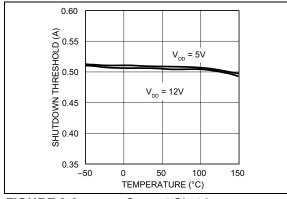


FIGURE 2-3: Current Shutdown Threshold vs. Temperature.

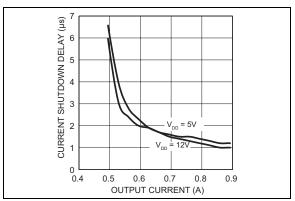


FIGURE 2-4: Current Shutdown Delay vs. Output Current.

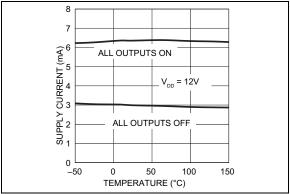


FIGURE 2-5: Supply Current vs. Temperature.

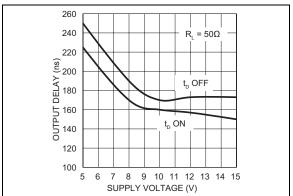


FIGURE 2-6: Output Delay vs. Supply Voltage.

3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 3-1.

TABLE 3-1: PIN FUNCTION TABLE

Pin Number PLCC	Pin Number SOIC	Pin Name	Description	
1	2	CLEAR	Resets all Latches and turns all outputs OFF (open).	
3	3	STROBE	Input Strobe Pin. Loads output latches when High.	
5, 6, 7, 8, 9, 10, 11, 12	4, 5, 6, 7, 8, 9, 10, 11	IN _N	Parallel Inputs, 1 through 8.	
15	1, 12	GROUND	Logic and Output Ground pin.	
17	13	COMMON	Transient suppression diode common cathode pin.	
18, 19, 20, 21, 22, 23, 24, 25	14, 15, 16, 17, 18, 19, 20, 21	OUT _N	Parallel Outputs, 8 through 1.	
27	22	V_{DD}	Logic Supply voltage.	
28	23	OUTPUT ENABLE/ RESET	When Low, Outputs are active. When High, outputs are inactive and device is reset from a fault condition. An undervoltage condition emulates a high $\overline{\text{OE}}$ output.	
2, 4, 13, 14, 16, 26	24	NC	No connect.	

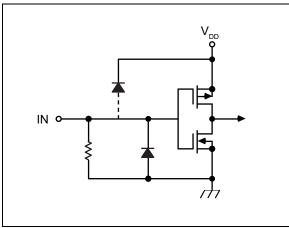


FIGURE 3-1: Typical Input.

4.0 TIMING

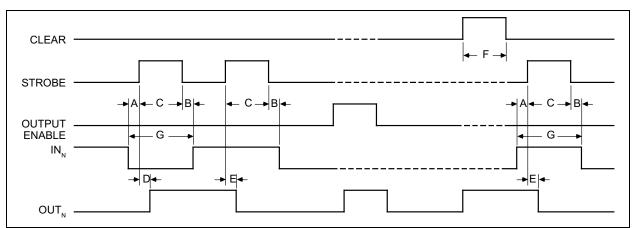


FIGURE 4-1: Timing Diagram.

TABLE 4-1: TIMING CONDITIONS

Characteristics: $T_A = +25$ °C; Logic levels are V_{DD} and Ground; $V_{DD} = 5V$.							
Condition	Min.	Тур.	Max.				
Minimum data active time before strobe enabled (data set-up time)	50 ns	_	_				
Minimum data active time after strobe disabled (data hold time)	50 ns	_	_				
Minimum strobe pulse width	125 ns	_	_				
Typical time between strobe activation and output on to off transition	_	500 ns	_				
Typical time between strobe activation and output off to on transition	_	500 ns	_				
Minimum clear pulse width	300 ns	_	_				
Minimum data pulse width	225 ns	_	_				

5.0 PACKAGING INFORMATION

5.1 Package Marking Information

28-Lead PLCC*





24-Lead SOICW*





Example

Legend: XX...X Product code or customer-specific information

Y Year code (last digit of calendar year)
YY Year code (last 2 digits of calendar year)
WW Week code (week of January 1 is week '01')

NNN Alphanumeric traceability code

(e3) Pb-free JEDEC® designator for Matte Tin (Sn)

This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

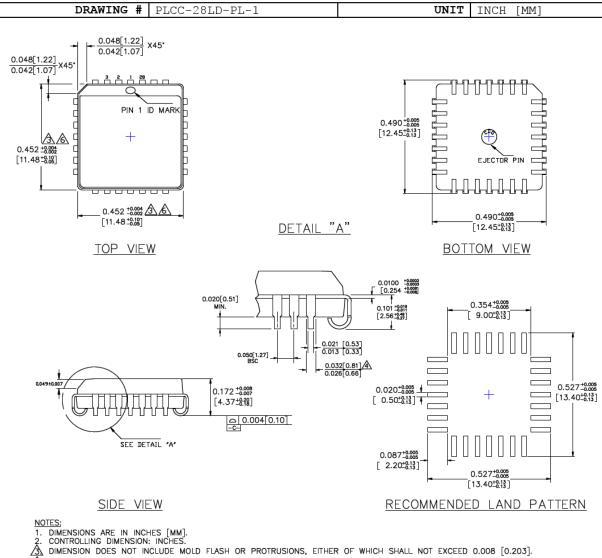
ullet, lacktriangle, lacktriangle Pin one index is identified by a dot, delta up, or delta down (triangle mark).

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information. Package may or may not include the corporate logo.

Underbar () and/or Overbar () symbol may not be to scale.

TITLE

28 LEAD PLCC PACKAGE OUTLINE & RECOMMENDED LAND PATTERN

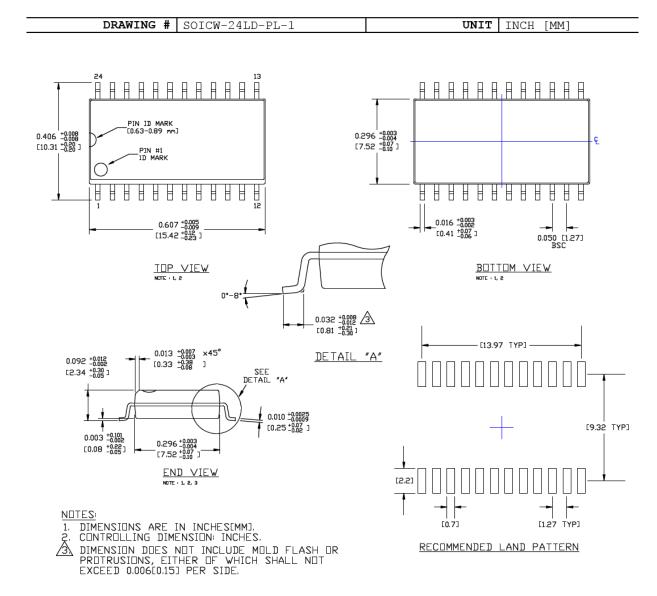


- DIMENSION DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS, EITHER OF WHICH SHALL NOT EXCEED 0.008 [0.203].
- LEAD DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION.
- MAXIMUM AND MINIMUM SPECIFICATIONS ARE INDICATED AS FOLLOWS: MAX/MIN
- PACKAGE TOP DIMENSION MAY BE SLIGHTLY SMALLER THAN BOTTOM DIMENSION.

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging.

TITLE

24 LEAD SOICW PACKAGE OUTLINE & RECOMMENDED LAND PATTERN



Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging.

NOTES:

APPENDIX A: REVISION HISTORY

Revision A (February 2019)

- Converted Micrel document MIC58P01 to Microchip data sheet template DS20006159A.
- Minor grammatical text changes throughout.

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

				Example	es:	
Device Part No.	<u>X</u> Junction Temp. Range	XX Package	- <u>XX</u> Media Type	a) MIC58	P01YV:	MIC58P01, -40°C to +85°C Temperature Range, 28-Lead PLCC, 38/Tube
Device:		Bit Parallel Input Pro	tected Latched	b) MIC58	P01YV-TR:	MIC58P01, -40°C to +85°C Temperature Range, 28-Leac PLCC, 750/Reel
Junction Temperature	Y = -40°C to	o +85°C, Industrial		c) MIC58	P01YWM:	MIC58P01, -40°C to +85°C Temperature Range, 24-Lead Wide SOIC, 31/Tube
Range: Package:	V = 28-Lead WM = 24-Lead	PLCC Wide SOIC		d) MIC58	P01YWM-TR:	MIC58P01, -40°C to +85°C Temperature Range, 24-Lead Wide SOIC, 1,000/Reel
Media Type:	 <blank>= 38/Tube <blank>= 31/Tube TR = 750/Ree</blank></blank>	(PLCC Package)		Note 1:	catalog part nun used for orderin the device pack	dentifier only appears in the nber description. This identifier is g purposes and is not printed on age. Check with your Microchip package availability with the ption.

NOTES:

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- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
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- Microchip is willing to work with the customer who is concerned about the integrity of their code.
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